## CRMGTH0706A

### N-Channel 68V, 5.8mΩ Typ. Power MOSFET

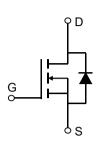
### **Description**

#### **Features**

• 68V, 83A

 $R_{DS(ON)}$  Typ = 5.8m $\Omega$  @  $V_{GS}$  = 10V

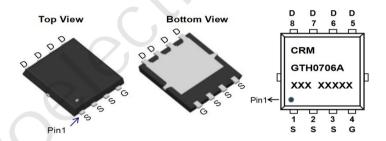
- Advanced Trench Technology
- Excellent R<sub>DS(ON)</sub> and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





## **Application**

- Load Switch
- PWM Application
- Power Management



**Marking and Pin Assignment** 

#### **Package Marking and Ordering Information**

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGTH0706A	CRMGTH0706A	PDFN5x6-8L	TAPING	13"	5000	50000

#### Absolute Maximum Ratings (@ T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{DS}$	Drain-to-Source Voltage		68	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T <sub>C</sub> = 25°C	83	Α
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 100°C	49.8	А
I <sub>DM</sub>	Pulsed Drain Current (1)		332	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (2)		248	mJ
$P_{D}$	Power Dissipation	T <sub>C</sub> = 25°C	89	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		1.4	°C/W
$T_J$ , $T_{STG}$	Junction & Storage Temperature Range		-55 to 150	°C



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### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	68	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 68V, V_{GS} = 0V$	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	3	3.6	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10V, I_D = 20A$	-	5.8	7.5	mΩ
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance		-	4960	-	pF
$C_{oss}$	Output Capacitance	$V_{GS} = 0V, V_{DS} = 25V,$ f = 1MHz	-	328	-	pF
$C_{rss}$	Reverse Transfer Capacitance	1 - 1101112	X -\	203	-	pF
Q <sub>g</sub>	Total Gate Charge		7	45	-	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 30V, I_{D} = 20A$	<b>U</b> .	17	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	V <sub>DS</sub> - 30V, I <sub>D</sub> - 20A	-	11	-	nC
Switchin	g Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime		-	22	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 30V$	-	80	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D$ = 30A, $R_{GEN}$ = 3 $\Omega$	-	50	-	ns
$t_{f}$	Turn-Off Fall Time		-	28	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	83	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	332	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I 00A 1771 400A7	-	35	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 30A$ , di/dt = 100A/us	-	54	_	nC

Notes:

<sup>1.</sup> Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

<sup>2.</sup> E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, R<sub>G</sub>=25ohm, L=0.5mH, I<sub>AS</sub>=31.5A

<sup>3.</sup> Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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### **Test Circuit**

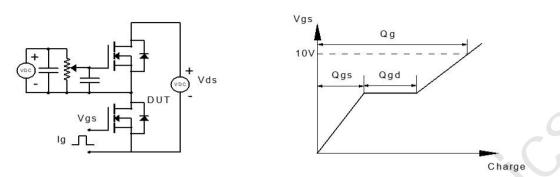


Figure 1: Gate Charge Test Circuit & Waveform

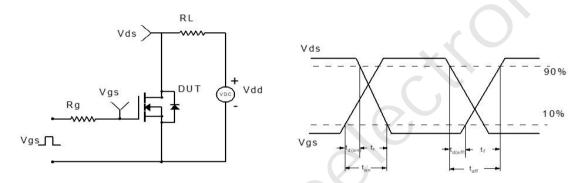


Figure 2: Resistive Switching Test Circuit & Waveform

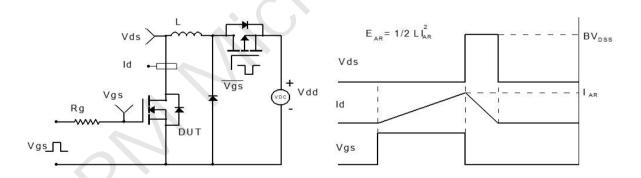


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

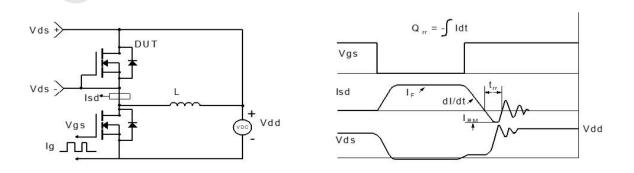
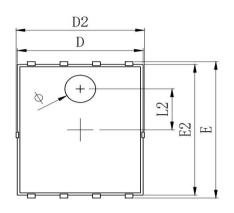


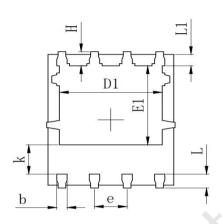
Figure 4: Diode Recovery Test Circuit & Waveform

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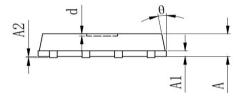
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## Package Mechanical Data(PDFN5x6-8L)





SYMBOL	MILLIMETER				
3 IMDUL	MIN	Typ.	MAX		
Α	0.900	1.000	1. 100		
A1	0.254 REF.				
A2	0~0.05				
D	4. 824	4. 900	4. 976		
D1	3. 910	4. 010	4. 110		
D2	4. 924	5. 000	5. 076		
Е	5. 924	6.000	6. 076		
E1	3. 375	3. 475	3. 575		
E2	5, 674	5. 750	5. 826		
b	0. 350	0.400	0. 450		
е	1.270 TYP.				
L	0. 534	0.610	0. 686		
L1	0. 424	0. 500	0. 576		
L2	1.800 REF.				
k	1. 190	1. 290	1. 390		
Н	0. 549	0.625	0. 701		
θ	8°	10°	12°		
ф	1.100	1.200	1.300		
d			0. 100		



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### **Contact information**

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